

**Amendments to the Claims:**

All claims have been amended herein. New claims 33-45 have been added. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1-12. (Canceled)

13. (Currently Amended) A method of making an FED having a central active display area and a surrounding peripheral area, comprising:  
making a cathode assembly;  
applying an etchant locally to uncover a structure in the peripheral area of the cathode assembly,  
including mutually moving an etchant dispenser and the cathode assembly during the  
applying;  
making an anode assembly, and  
assembling said cathode and anode assemblies;  
~~wherein said step of making a cathode assembly includes the step of locally applying an~~  
~~etchant to uncover a structure in the peripheral area of the cathode assembly.~~

14. (Currently Amended) The method of ~~Claim 13 wherein said~~ claim 13, wherein  
the structure comprises an alignment mark.

15. (Currently Amended) The method of ~~Claim 13 wherein said~~ claim 13, wherein  
the structure comprises a bond pad.

16. (Currently Amended) The method of ~~Claim 13 wherein said~~ claim 13, wherein  
the step of locally applying an etchant comprises spraying a wet etchant on the structure without

spraying the etchant elsewhere.

17. (Currently Amended) A method of making an FED having a central active display area and a surrounding peripheral region, comprising:  
making a cathode assembly,  
making an anode assembly,  
locally applying an etchant to uncover a structure in the peripheral region of the anode assembly,  
including mutually moving an etchant dispenser and the anode assembly during the  
applying; and  
assembling said cathode and anode assemblies,  
~~wherein said step of making an anode assembly includes the step of locally applying an~~  
~~etchant to uncover a structure in the peripheral region of the cathode assembly.~~

18. (Currently Amended) The method of ~~Claim 17 wherein said~~ claim 17, wherein  
the structure comprises an alignment mark.

19. (Currently Amended) The method of ~~Claim 17 wherein said~~ claim 17, wherein  
the step of locally applying an etchant comprises spraying a wet etchant on the structure while  
limiting spraying of the etchant elsewhere.

20. (Currently Amended) A method of forming a cathode assembly of an FED,  
comprising:  
providing a substrate having a central area and a peripheral area;  
forming alignment marks on the peripheral area of the substrate;  
forming an emitter electrode structure on the central area of the substrate;  
forming a plurality of micropoints in groups on the emitter electrode structure;  
depositing an insulating layer over the substrate, emitter electrode structure, and plurality of  
micropoints;  
depositing a conductive layer over the insulating layer;

locally applying etchant on the alignment marks, including mutually moving an etchant dispenser and the substrate; and  
selectively etching openings through the conductive and insulating layers to expose the micropoints, with walls defining the openings being spaced away from the micropoints.

21. (Currently Amended) The method of ~~Claim 20 wherein~~ claim 20, wherein selectively etching openings through the conductive and insulating layers comprises applying a layer of photoresist on said conductive layer, imaging said photoresist to define a pattern for said openings, developing the photoresist, and etching the pattern for the openings.

22. (Currently Amended) The method of ~~Claim 21 further~~ claim 21, further comprising the step of polishing the conductive layer after the step of depositing a conductive layer over the insulating layer.

23. (Currently Amended) The method of ~~Claim 22 wherein said~~ claim 22, wherein the step of polishing comprises chemical-mechanical planarization.

24. (Currently Amended) The method of ~~Claim 21 wherein said~~ claim 21, wherein the step of locally applying an etchant comprises spraying a wet etchant on the alignment marks without spraying the etchant elsewhere.

25. (Currently Amended) A method of forming a cathode assembly of a field emission device, comprising:  
providing a substrate;  
making alignment marks in a peripheral region of the substrate;  
forming an emitter electrode structure on a central region of the substrate, said central region being substantially surrounded by the peripheral region;  
forming a plurality of micropoints on the emitter electrode structure;  
depositing an insulating layer over the substrate, emitter electrode structure, and plurality of

micropoints;  
depositing a first conductive layer over the insulating layer;  
polishing the conductive layer;  
selectively applying localized etchant on the alignment marks while inhibiting application of the etchant on the central region to clear the marks of material deposited thereon, including mutually moving an etchant dispenser and the substrate during the applying; and  
etching openings through the conductive and insulating layers to expose the micropoints, with walls defining the openings being spaced away from the micropoints.

26. (Currently Amended) The method of ~~Claim 25 wherein said~~ claim 25, wherein the step of selectively applying a localized etchant comprises spraying a wet etchant on the alignment marks.

27-32. (Canceled)

33. (New) The method of claim 13, wherein mutually moving comprises moving the etchant dispenser relative to the cathode assembly.

34. (New) The method of claim 13, wherein mutually moving comprises moving the cathode assembly relative to the etchant dispenser.

35. (New) The method of claim 15, further comprising applying the etchant on the bond pads in elongated spray zones.

36. (New) The method of claim 35, further comprising spraying the etchant from a nozzle in the etchant dispenser while moving the nozzle linearly over the cathode assembly.

37. (New) The method of claim 17, wherein mutually moving comprises moving the etchant dispenser relative to the anode assembly.

38. (New) The method of claim 17, wherein mutually moving comprises moving the anode assembly relative to the etchant dispenser.

39. (New) The method of claim 17, wherein the structure comprises at least one bond pad.

40. (New) The method of claim 39, further comprising applying the etchant on the at least one bond pad in elongated spray zones.

41. (New) The method of claim 40, further comprising spraying the etchant from a nozzle in the etchant dispenser while moving the nozzle linearly over the cathode assembly.

42. (New) The method of claim 20, wherein mutually moving comprises moving the etchant dispenser relative to the substrate.

43. (New) The method of claim 20, wherein mutually moving comprises moving the substrate relative to the etchant dispenser.

44. (New) The method of claim 25, wherein mutually moving comprises moving the etchant dispenser relative to the substrate.

45. (New) The method of claim 25, wherein mutually moving comprises moving the substrate relative to the etchant dispenser.